

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	26	361/735.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:38
S14	2	361/772.ccls. and (gold adj1 bond\$ and pad\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S17	2	361/745.ccls. and (bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:24
S19	2	361/790.ccls. and (pads) and (solder adj1 resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S21	69	"361"/\$.ccls. and (wire adj1 bond\$) and (solder adj1 resist)and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:25
S24	28	361/735.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:16
S25	148	levi adj1 dameon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 17:34
S26	7	("4928206" "5224023" "5754409" "5789815" "5995370" "6208521").PN. OR ("6469903").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/11 17:36
S27	58	("4996587" "5012323" "5019943" "5049676" "5291061" "5323060" "5399898" "5422435").PN. OR ("6005778").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/11 18:14
S28	10	("5474957" "5663530").PN. OR ("6040984").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/11 18:15

S29	7	("5793108" "5998864" "6051886" "6252305").PN. OR ("6359340").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/11 18:15
S30	415	257/686.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:26
S31	76	257/686.ccls. and (wire adj1 bond\$) and gold and (resist and solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:17
S32	60	257/686.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20
S33	36	257/686.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and (bond\$ adj1 pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:17
S34	47	257/692.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20
S35	57	257/777.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20
S36	39	257/779.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20
S37	79	257/784.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:22
S38	45	257/786.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20

S39	78	257/E25.013.ccls. and (wire adj1 bond\$) and gold and (resist and solder) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:20
S40	28	361/735.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S41	170	361/760.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S42	2	361/790.ccls. and (pads) and (solder adj1 resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S43	2	361/772.ccls. and (gold adj1 bond\$ and pad\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S44	67	361/772.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:23
S45	2	361/745.ccls. and (bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:24
S46	71	"361"/\$.ccls. and (wire adj1 bond\$) and (solder adj1 resist) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:24
S47	71	"361"/\$.ccls. and (wire adj1 bond\$) and (solder adj1 resist) and pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:25
S48	71	174/250.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:27

S49	45	174/255.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:27
S50	34	174/256.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:28
S51	25	174/257.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:28
S52	21	174/258.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:29
S53	49	174/261.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:30
S54	13	174/263.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:30
S55	16	174/267.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:32
S56	9	361/748.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:33
S57	23	361/783.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S58	20	("3296099" "3977074" "3996416" "4864471").PN. OR ("4996629").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/11 18:37

S59	3	361/735.ccls. and (wire adj1 bond\$) and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:39
S60	4	361/735.ccls. and (goldadj1 bond\$) and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:39
S62	1	361/735.ccls. and (gold adj1 bond\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:39
S63	7	361/773.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S64	23	361/774.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S65	15	361/776.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S66	25	361/777.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S68	10	361/779.ccls. and (wire adj1 bond\$) and gold and solder and resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:54
S69	10	361/778.ccls. and (wire adj1 bond\$) and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/11 18:55